

### **Amendments to the Claims:**

*This listing of claims will replace all prior versions, and listings, of claims in the application:*

1. (Previously Amended) A method of applying a solder filler to an aluminum body part, said method comprising the steps of:

applying a fluxing agent in paste-like form to the aluminum body part;

heating the applied fluxing agent to deoxidize the surface of the aluminum body part;

applying a tin-based solder filler to the deoxidized surface of the aluminum body part, the melting point temperature of the solder filler being at least 100 degrees C lower than the melting point temperature of the aluminum body part and the tin-based solder filler consists of, by weight, of 81% to 85% Sn, 3% to 5% Zn, and 12% to 14% Cu; and

heating the solder filler to bond the solder filler to the aluminum body part.

2-5. (Canceled).

6. (Previously Amended) The method of claim 21 wherein the solder filler consists of, by weight, 66.5% Sn, 30% Zn, and 3.5% Ni.

7. (Currently Amended) The method of claim 22 wherein the solder filler consists of, by weight, of ~~80%~~ 79.5% Zn and ~~20%~~ 20.5% Al.

8. (Original) The method of claim 1 further comprises washing the aluminum body part to remove flux residue created during the heating step.

9. (Original) The method of claim 1 wherein the fluxing agent is comprised of a combination of organic compounds and metallic salts.

10. (Original) The method of claim 1 wherein the fluxing agent is comprised of a combination of complex organometallic salts.

11. (Previously Amended) A method of applying a solder filler to an aluminum body part comprising the steps of:

forming a filler/flux mixture comprising a tin-based solder filler for aluminum body parts and a fluxing agent wherein the melting point temperature of the solder filler is at least 100 degrees C lower than the melting point temperature of the aluminum body part and the tin-based solder filler consists of, by weight, of 81% to 85% Sn, 3% to 5% Zn, and 12% to 14% Cu;

applying the filler/flux mixture to the aluminum body part; and

heating the filler/flux mixture to bond the solder filler to the aluminum body part.

12-14. (Canceled) /

15. (Original) The method of claim 11 wherein the fluxing agent is comprised of a combination of organic compounds and metallic salts.

16. (Original) The method of claim 11 wherein the fluxing agent is comprised of a combination of complex organometallic salts.

17. (Previously Amended) The method of claim 11 wherein the filler/flux mixture is comprised of by weight about 10% of the fluxing agent and about 90% of the tin-based solder filler.

18. (Canceled) /

19. (Withdrawn)

20. (Withdrawn)

21. (Previously Added) A method of applying a solder filler to an aluminum body part, said method comprising the steps of:

applying a fluxing agent in paste-like form to the aluminum body part;  
heating the applied fluxing agent to deoxidize the surface of the aluminum body part;

applying a tin-based solder filler to the deoxidized surface of the aluminum body part, the melting point temperature of the solder filler being at least 100 degrees C lower than the melting point temperature of the aluminum body part and the tin-based solder filler consists of, by weight, of 55% to 85% Sn, 12% to 40% Zn, and 3% to 5% Ni, Fe, Cu or Co; and  
heating the solder filler to bond the solder filler to the aluminum body part.

22. (Currently Amended) A method of applying a solder filler to an aluminum body part, said method comprising the steps of:

applying a fluxing agent in paste-like form to the aluminum body part;  
heating the applied fluxing agent to deoxidize the surface of the aluminum body part;

applying a zinc-based solder filler to the deoxidized surface of the aluminum body part, the melting point temperature of the solder filler being at least 100 degrees C lower than the melting point temperature of the aluminum body part and the zinc-based solder filler consists of, by weight, of ~~78% to 89%~~ 78% to 79.5% Zn and ~~11% to 22%~~ 20.5% to 22% Al;  
and

heating the solder filler to bond the solder filler to the aluminum body part.

23. (Previously Added) The method of claim 11 wherein the forming step is comprised of providing the tin-based solder filler in the form of a hollow wire and injecting the fluxing agent into the hollow wire.